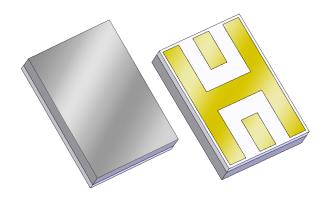


### **Applications**

- L-Band
- For high-selectivity applications



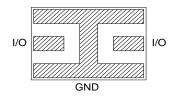
### Product Features

- Usable bandwidth 19 MHz
- Low loss
- High selectivity
- Single-ended operation
- Ceramic chip-scale Package (CSP)
- Small Size
- Hermetic RoHS compliant, Pb-free

### Pin Configuration

Pin # SE-Balanced	Description
I/O	Input/Output
GND	Ground

# Functional Block Diagram



Overall width, length, and thickness are the only critical dimensions. All other dimensions are for reference only.

Dimensions shown are nominal in millimeters All tolerances are  $\pm 0.13$ mm except overall length and width  $\pm 0.25$ mm

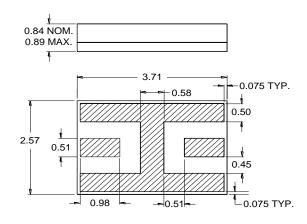
Body: *Sapphire* Package: *Alumina* 

Terminations: Au plating 0.5 - 2.5μm, over a 2.0 – 6.0 μm Ni plating

## **Ordering Information**

Part No.	Description
880368	packaged part
880368 Eval Board	evaluation board

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### **Specifications**

# **Electrical Specifications** (1)

Specified Temperature Range: (2) -40 to +85 °C

pecifical remperature range. To to 105 C						
Parameter (3)	Conditions	Min	Typical <sup>(4)</sup>	Max	Units	
Center Frequency		-	1280	-	MHz	
Maximum Insertion Loss	@ 1280 MHz	-	4.0	4.5	dB	
3dB Bandwidth	Reference loss at 1280 MHz	19	23	-	MHz	
40dB Lower Frequency Edge		1249	1260	-	MHz	
40dB Upper Frequency Edge		-	1300	1311	MHz	
VSWR	@ 1280 MHz	-	1.5	2.0	-	
Source Impedance (single-ended) (5)		-	50	-	Ω	
Load Impedance (single-ended) (5)		-	50	-	Ω	

#### Notes

- 1. All specifications are based on the TriQuint schematic for the main reference design shown on page 3
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature

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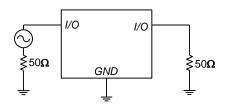
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 4. Typical values are based on average measurements at room temperature
- 5. This is the optimum impedance in order to achieve the performance shown



### Reference Design

#### **Schematic**



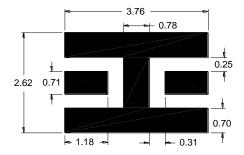


 $\begin{array}{c} 50~\Omega\\ \text{Single-ended}\\ \text{Input} \end{array}$ 

#### **PC Board**

Refer to **PCB Layout** for more information.

### **Mounting Configuration**

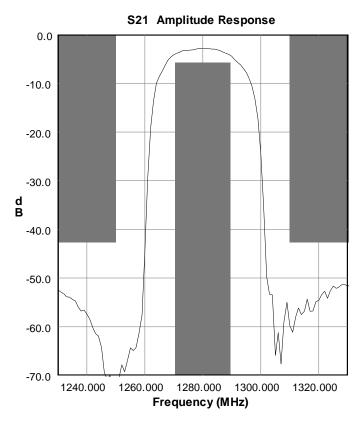


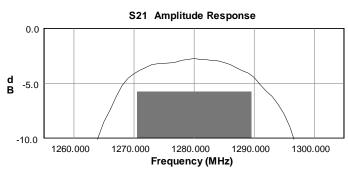
#### Notes:

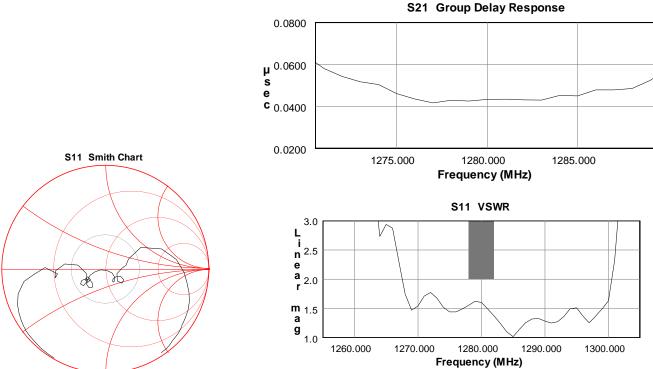
- 1. All dimensions are in millimeters.
- 2. This footprint represents a recommendation only.



### Typical Performance (at room temperature)





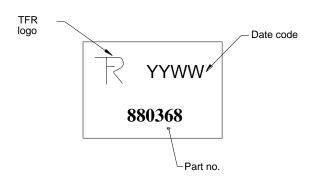


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### **Mechanical Information**

### Marking



The date code consists of: YY = last digit of year, WW = 2 digit week

### **Tape and Reel Information**

Tape and Reel available upon request EIA-481

Tinning available per J-STD-001

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### **Absolute Maximum Ratings**

Parameter	Rating
Operating Temperature	-40 to +85 °C
Storage Temperature	-55 to +100 °C
Maximum Input Power	+23 dBm

Operation of this device outside the parameter ranges given above may cause permanent damage.